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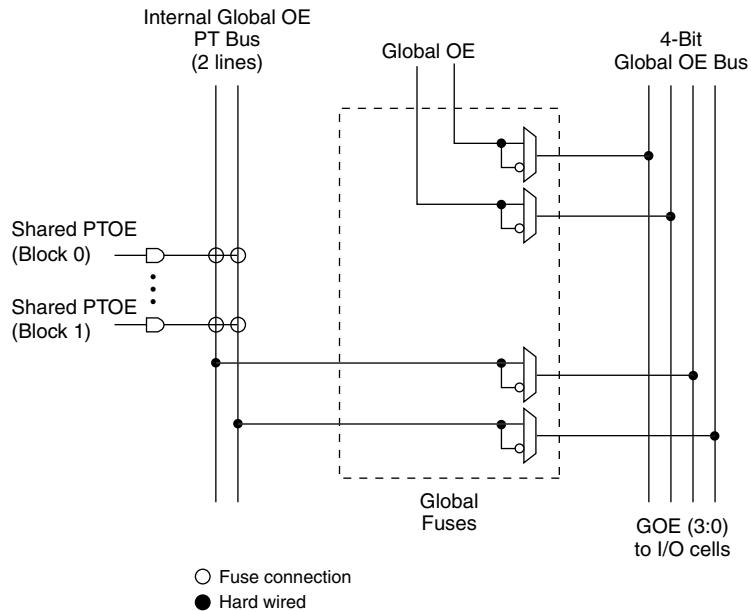
### Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

### **Applications of Embedded - CPLDs**

#### **Details**

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	5 ns
Voltage Supply - Internal	1.65V ~ 1.95V
Number of Logic Elements/Blocks	4
Number of Macrocells	64
Number of Gates	-
Number of I/O	32
Operating Temperature	-40°C ~ 105°C (TJ)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-TQFP (7x7)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4064c-5t48i">https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4064c-5t48i</a>

**Figure 10. Global OE Generation for ispMACH 4032**

## Zero Power/Low Power and Power Management

The ispMACH 4000 family is designed with high speed low power design techniques to offer both high speed and low power. With an advanced E<sup>2</sup> low power cell and non sense-amplifier design approach (full CMOS logic approach), the ispMACH 4000 family offers SuperFAST pin-to-pin speeds, while simultaneously delivering low standby power without needing any “turbo bits” or other power management schemes associated with a traditional sense-amplifier approach.

The zero power ispMACH 4000Z is based on the 1.8V ispMACH 4000C family. With innovative circuit design changes, the ispMACH 4000Z family is able to achieve the industry’s “lowest static power”.

## IEEE 1149.1-Compliant Boundary Scan Testability

All ispMACH 4000 devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more board-level testing. The test access port operates with an LVCMOS interface that corresponds to the power supply voltage.

## I/O Quick Configuration

To facilitate the most efficient board test, the physical nature of the I/O cells must be set before running any continuity tests. As these tests are fast, by nature, the overhead and time that is required for configuration of the I/Os’ physical nature should be minimal so that board test time is minimized. The ispMACH 4000 family of devices allows this by offering the user the ability to quickly configure the physical nature of the I/O cells. This quick configuration takes milliseconds to complete, whereas it takes seconds for the entire device to be programmed. Lattice's ispVM® System programming software can either perform the quick configuration through the PC parallel port, or can generate the ATE or test vectors necessary for a third-party test system.

## I/O Recommended Operating Conditions

Standard	$V_{CCO}$ (V) <sup>1</sup>	
	Min.	Max.
LV TTL	3.0	3.6
LVC MOS 3.3	3.0	3.6
Extended LVC MOS 3.3 <sup>2</sup>	2.7	3.6
LVC MOS 2.5	2.3	2.7
LVC MOS 1.8	1.65	1.95
PCI 3.3	3.0	3.6

1. Typical values for  $V_{CCO}$  are the average of the min. and max. values.

2. ispMACH 4000Z only.

## DC Electrical Characteristics

### Over Recommended Operating Conditions

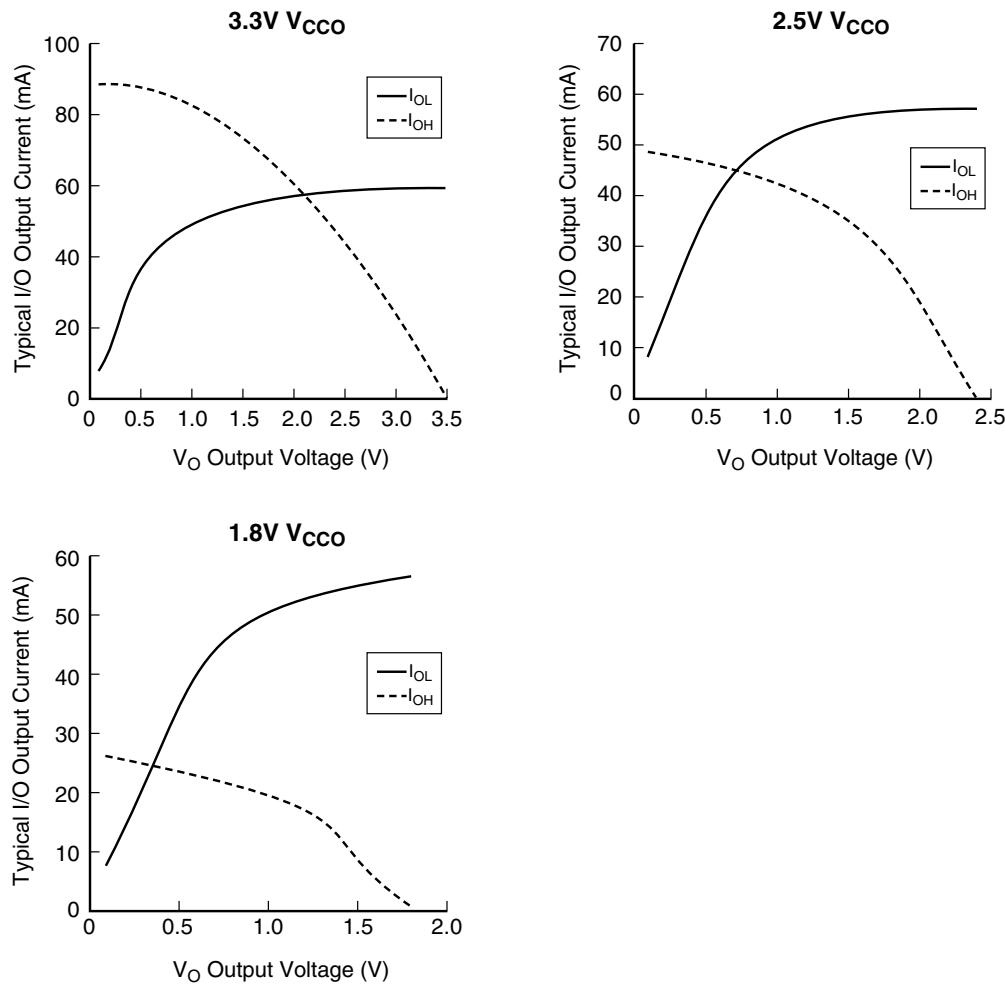
Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$I_{IL}, I_{IH}^{1,4}$	Input Leakage Current (ispMACH 4000Z)	$0 \leq V_{IN} < V_{CCO}$	—	0.5	1	$\mu A$
$I_{IH}^1$	Input High Leakage Current (ispMACH 4000Z)	$V_{CCO} < V_{IN} \leq 5.5V$	—	—	10	$\mu A$
$I_{IL}, I_{IH}^1$	Input Leakage Current (ispMACH 4000V/B/C)	$0 \leq V_{IN} \leq 3.6V, T_j = 105^\circ C$ $0 \leq V_{IN} \leq 3.6V, T_j = 130^\circ C$	—	—	10	$\mu A$
$I_{IH}^{1,2}$	Input High Leakage Current (ispMACH 4000V/B/C)	$3.6V < V_{IN} \leq 5.5V, T_j = 105^\circ C$ $3.0V \leq V_{CCO} \leq 3.6V$	—	—	20	$\mu A$
$I_{IH}^{1,2}$		$3.6V < V_{IN} \leq 5.5V, T_j = 130^\circ C$ $3.0V \leq V_{CCO} \leq 3.6V$	—	—	50	$\mu A$
$I_{PU}$	I/O Weak Pull-up Resistor Current (ispMACH 4000Z)	$0 \leq V_{IN} \leq 0.7V_{CCO}$	-30	—	-150	$\mu A$
$I_{PU}$	I/O Weak Pull-up Resistor Current (ispMACH 4000V/B/C)	$0 \leq V_{IN} \leq 0.7V_{CCO}$	-30	—	-200	$\mu A$
$I_{PD}$	I/O Weak Pull-down Resistor Current	$V_{IL} (\text{MAX}) \leq V_{IN} \leq V_{IH} (\text{MIN})$	30	—	150	$\mu A$
$I_{BHLS}$	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL} (\text{MAX})$	30	—	—	$\mu A$
$I_{BHHS}$	Bus Hold High Sustaining Current	$V_{IN} = 0.7 V_{CCO}$	-30	—	—	$\mu A$
$I_{BHLO}$	Bus Hold Low Overdrive Current	$0V \leq V_{IN} \leq V_{BHT}$	—	—	150	$\mu A$
$I_{BHHO}$	Bus Hold High Overdrive Current	$V_{BHT} \leq V_{IN} \leq V_{CCO}$	—	—	-150	$\mu A$
$V_{BHT}$	Bus Hold Trip Points	—	$V_{CCO} * 0.35$	—	$V_{CCO} * 0.65$	V
$C_1$	I/O Capacitance <sup>3</sup>	$V_{CCO} = 3.3V, 2.5V, 1.8V$ $V_{CC} = 1.8V, V_{IO} = 0 \text{ to } V_{IH} (\text{MAX})$	—	8	—	pf
$C_2$	Clock Capacitance <sup>3</sup>	$V_{CCO} = 3.3V, 2.5V, 1.8V$ $V_{CC} = 1.8V, V_{IO} = 0 \text{ to } V_{IH} (\text{MAX})$	—	6	—	pf
$C_3$	Global Input Capacitance <sup>3</sup>	$V_{CCO} = 3.3V, 2.5V, 1.8V$ $V_{CC} = 1.8V, V_{IO} = 0 \text{ to } V_{IH} (\text{MAX})$	—	6	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tristated. It is not measured with the output driver active. Bus maintenance circuits are disabled.

2. 5V tolerant inputs and I/O should only be placed in banks where  $3.0V \leq V_{CCO} \leq 3.6V$ .

3.  $T_A = 25^\circ C, f = 1.0MHz$

4.  $I_{IH}$  excursions of up to  $1.5\mu A$  maximum per pin above the spec limit may be observed for certain voltage conditions on no more than 10% of the device's I/O pins.





**ispMACH 4000Z Internal Timing Parameters (Cont.)**

Over Recommended Operating Conditions

Parameter	Description	-45		-5		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t <sub>PTOE</sub>	Macrocell PT OE Delay	—	2.50	—	2.70	—	2.00	ns

Note: Internal Timing Parameters are not tested and are for reference only. Refer to the timing model in this data sheet for further details.

Timing v.2.2

**ispMACH 4000V/B/C Timing Adders<sup>1</sup>**

Adder Type	Base Parameter	Description	-25		-27		-3		-35		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
<b>Optional Delay Adders</b>											
$t_{INDIO}$	$t_{INREG}$	Input register delay	—	0.95	—	1.00	—	1.00	—	1.00	ns
$t_{EXP}$	$t_{MCELL}$	Product term expander delay	—	0.33	—	0.33	—	0.33	—	0.33	ns
$t_{ORP}$	—	Output routing pool delay	—	0.05	—	0.05	—	0.05	—	0.05	ns
$t_{BLA}$	$t_{ROUTE}$	Additional block loading adder	—	0.03	—	0.05	—	0.05	—	0.05	ns
<b><math>t_{IOI}</math> Input Adjusters</b>											
LVTTL_in	$t_{IN}$ , $t_{GCLK\_IN}$ , $t_{GOE}$	Using LVTTL standard	—	0.60	—	0.60	—	0.60	—	0.60	ns
LVCMOS33_in	$t_{IN}$ , $t_{GCLK\_IN}$ , $t_{GOE}$	Using LVCMOS 3.3 standard	—	0.60	—	0.60	—	0.60	—	0.60	ns
LVCMOS25_in	$t_{IN}$ , $t_{GCLK\_IN}$ , $t_{GOE}$	Using LVCMOS 2.5 standard	—	0.60	—	0.60	—	0.60	—	0.60	ns
LVCMOS18_in	$t_{IN}$ , $t_{GCLK\_IN}$ , $t_{GOE}$	Using LVCMOS 1.8 standard	—	0.00	—	0.00	—	0.00	—	0.00	ns
PCI_in	$t_{IN}$ , $t_{GCLK\_IN}$ , $t_{GOE}$	Using PCI compatible input	—	0.60	—	0.60	—	0.60	—	0.60	ns
<b><math>t_{IOO}</math> Output Adjusters</b>											
LVTTL_out	$t_{BUF}$ , $t_{EN}$ , $t_{DIS}$	Output configured as TTL buffer	—	0.20	—	0.20	—	0.20	—	0.20	ns
LVCMOS33_out	$t_{BUF}$ , $t_{EN}$ , $t_{DIS}$	Output configured as 3.3V buffer	—	0.20	—	0.20	—	0.20	—	0.20	ns
LVCMOS25_out	$t_{BUF}$ , $t_{EN}$ , $t_{DIS}$	Output configured as 2.5V buffer	—	0.10	—	0.10	—	0.10	—	0.10	ns
LVCMOS18_out	$t_{BUF}$ , $t_{EN}$ , $t_{DIS}$	Output configured as 1.8V buffer	—	0.00	—	0.00	—	0.00	—	0.00	ns
PCI_out	$t_{BUF}$ , $t_{EN}$ , $t_{DIS}$	Output configured as PCI compatible buffer	—	0.20	—	0.20	—	0.20	—	0.20	ns
Slow Slew	$t_{BUF}$ , $t_{EN}$	Output configured for slow slew rate	—	1.00	—	1.00	—	1.00	—	1.00	ns

Note: Open drain timing is the same as corresponding LVCMOS timing.

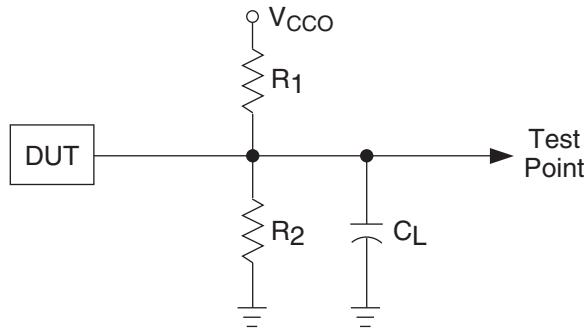
Timing v.3.2

1. Refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#) for information regarding use of these adders.

## Switching Test Conditions

Figure 12 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Table 11.

**Figure 12. Output Test Load, LVTTL and LVC MOS Standards**



0213A/ispm4k

**Table 11. Test Fixture Required Components**

Test Condition	R <sub>1</sub>	R <sub>2</sub>	C <sub>L</sub> <sup>1</sup>	Timing Ref.	V <sub>CCO</sub>
LVC MOS I/O, (L → H, H → L)	106Ω	106Ω	35pF	LVC MOS 3.3 = 1.5V	LVC MOS 3.3 = 3.0V
				LVC MOS 2.5 = V <sub>CCO</sub> /2	LVC MOS 2.5 = 2.3V
				LVC MOS 1.8 = V <sub>CCO</sub> /2	LVC MOS 1.8 = 1.65V
LVC MOS I/O (Z → H)	∞	106Ω	35pF	1.5V	3.0V
LVC MOS I/O (Z → L)	106Ω	∞	35pF	1.5V	3.0V
LVC MOS I/O (H → Z)	∞	106Ω	5pF	V <sub>OH</sub> - 0.3	3.0V
LVC MOS I/O (L → Z)	106Ω	∞	5pF	V <sub>OL</sub> + 0.3	3.0V

1. C<sub>L</sub> includes test fixtures and probe capacitance.

**ispMACH 4032V/B/C and 4064V/B/C Logic Signal Connections:  
44-Pin TQFP**

Pin Number	Bank Number	ispMACH 4032V/B/C		ispMACH 4064V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	TDI	-	TDI	-
2	0	A5	A^5	A10	A^5
3	0	A6	A^6	A12	A^6
4	0	A7	A^7	A14	A^7
5	0	GND (Bank 0)	-	GND (Bank 0)	-
6	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
7	0	A8	A^8	B0	B^0
8	0	A9	A^9	B2	B^1
9	0	A10	A^10	B4	B^2
10	-	TCK	-	TCK	-
11	-	VCC	-	VCC	-
12	-	GND	-	GND	-
13	0	A12	A^12	B8	B^4
14	0	A13	A^13	B10	B^5
15	0	A14	A^14	B12	B^6
16	0	A15	A^15	B14	B^7
17	1	CLK2/I	-	CLK2/I	-
18	1	B0	B^0	C0	C^0
19	1	B1	B^1	C2	C^1
20	1	B2	B^2	C4	C^2
21	1	B3	B^3	C6	C^3
22	1	B4	B^4	C8	C^4
23	-	TMS	-	TMS	-
24	1	B5	B^5	C10	C^5
25	1	B6	B^6	C12	C^6
26	1	B7	B^7	C14	C^7
27	1	GND (Bank 1)	-	GND (Bank 1)	-
28	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
29	1	B8	B^8	D0	D^0
30	1	B9	B^9	D2	D^1
31	1	B10	B^10	D4	D^2
32	-	TDO	-	TDO	-
33	-	VCC	-	VCC	-
34	-	GND	-	GND	-
35	1	B12	B^12	D8	D^4
36	1	B13	B^13	D10	D^5
37	1	B14	B^14	D12	D^6
38	1	B15/GOE1	B^15	D14/GOE1	D^7
39	0	CLK0/I	-	CLK0/I	-
40	0	A0/GOE0	A^0	A0/GOE0	A^0
41	0	A1	A^1	A2	A^1

**ispMACH 4032V/B/C/Z and 4064V/B/C/Z Logic Signal Connections:  
48-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4032V/B/C/Z		ispMACH 4064V/B/C		ispMACH 4064Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
33	1	B10	B^10	D4	D^2	D10	D^5
34	1	B11	B^11	D6	D^3	D8	D^4
35	-	TDO	-	TDO	-	TDO	-
36	-	VCC	-	VCC	-	VCC	-
37	-	GND	-	GND	-	GND	-
38	1	B12	B^12	D8	D^4	D6	D^3
39	1	B13	B^13	D10	D^5	D4	D^2
40	1	B14	B^14	D12	D^6	D2	D^1
41	1	B15/GOE1	B^15	D14/GOE1	D^7	D0/GOE1	D^0
42	1	CLK3/I	-	CLK3/I	-	CLK3/I	-
43	0	CLK0/I	-	CLK0/I	-	CLK0/I	-
44	0	A0/GOE0	A^0	A0/GOE0	A^0	A0/GOE0	A^0
45	0	A1	A^1	A2	A^1	A1	A^1
46	0	A2	A^2	A4	A^2	A2	A^2
47	0	A3	A^3	A6	A^3	A4	A^3
48	0	A4	A^4	A8	A^4	A6	A^4

**ispMACH 4032Z and 4064Z Logic Signal Connections: 56-Ball csBGA**

Ball Number	Bank Number	ispMACH 4032Z		ispMACH 4064Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
B1	-	TDI	-	TDI	-
C3	0	A5	A^5	A8	A^5
C1	0	A6	A^6	A10	A^6
D1	0	A7	A^7	A11	A^7
D3	0	GND (Bank 0)	-	GND (Bank 0)	-
E3	0	NC <sup>1</sup>	-	I <sup>1</sup>	-
E1	0	NC <sup>1</sup>	-	I <sup>1</sup>	-
F3	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
F1	0	A8	A^8	B15	B^7
G3	0	A9	A^9	B12	B^6
G1	0	A10	A^10	B10	B^5
H1	0	A11	A^11	B8	B^4
J1	0	NC	-	I	-
K1	-	TCK	-	TCK	-
K2	-	VCC	-	VCC	-
H3	-	GND	-	GND	-
K3	-	NC <sup>1</sup>	-	I <sup>1</sup>	-
K4	0	A12	A^12	B6	B^3
H4	0	A13	A^13	B4	B^2
H5	0	A14	A^14	B2	B^1

**ispMACH 4128V and 4256V Logic Signal Connections: 144-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4128V		ispMACH 4256V	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
43	0	D9	D^7	G4	G^2
44	0	D8	D^6	G2	G^1
45	0	NC <sup>2</sup>	-	I <sup>2</sup>	-
46	0	GND (Bank 0)	-	GND (Bank 0)	-
47	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
48	0	D6	D^5	H12	H^6
49	0	D5	D^4	H10	H^5
50	0	D4	D^3	H8	H^4
51	0	D2	D^2	H6	H^3
52	0	D1	D^1	H4	H^2
53	0	D0	D^0	H2	H^1
54	0	CLK1/I	-	CLK1/I	-
55	1	GND (Bank 1)	-	GND (Bank 1)	-
56	1	CLK2/I	-	CLK2/I	-
57	-	VCC	-	VCC	-
58	1	E0	E^0	I2	I^1
59	1	E1	E^1	I4	I^2
60	1	E2	E^2	I6	I^3
61	1	E4	E^3	I8	I^4
62	1	E5	E^4	I10	I^5
63	1	E6	E^5	I12	I^6
64	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
65	1	GND (Bank 1)	-	GND (Bank 1)	-
66	1	E8	E^6	J2	J^1
67	1	E9	E^7	J4	J^2
68	1	E10	E^8	J6	J^3
69	1	E12	E^9	J8	J^4
70	1	E13	E^10	J10	J^5
71	1	E14	E^11	J12	J^6
72	1	NC <sup>2</sup>	-	I <sup>2</sup>	-
73	-	GND	-	GND	-
74	-	TMS	-	TMS	-
75	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
76	1	F0	F^0	K12	K^6
77	1	F1	F^1	K10	K^5
78	1	F2	F^2	K8	K^4
79	1	F4	F^3	K6	K^3
80	1	F5	F^4	K4	K^2
81	1	F6	F^5	K2	K^1
82	1	GND (Bank 1)	-	GND (Bank 1)	-
83	1	F8	F^6	L14	L^7
84	1	F9	F^7	L12	L^6
85	1	F10	F^8	L10	L^5

**ispMACH 4256V/B/C/Z, 4384V/B/C, 4512V/B/C, Logic Signal Connections:  
176-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4256V/B/C/Z		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
60	0	H8	H^4	L8	L^4	P8	P^4
61	0	H6	H^3	L6	L^3	P6	P^3
62	0	H4	H^2	L4	L^2	P4	P^2
63	0	H2	H^1	L2	L^1	P2	P^1
64	0	H0	H^0	L0	L^0	P0	P^0
65	-	GND	-	GND	-	GND	-
66	0	CLK1/I	-	CLK1/I	-	CLK1/I	-
67	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
68	1	CLK2/I	-	CLK2/I	-	CLK2/I	-
69	-	VCC	-	VCC	-	VCC	-
70	1	I0	I^0	M0	M^0	AX0	AX^0
71	1	I2	I^1	M2	M^1	AX2	AX^1
72	1	I4	I^2	M4	M^2	AX4	AX^2
73	1	I6	I^3	M6	M^3	AX6	AX^3
74	1	I8	I^4	M8	M^4	AX8	AX^4
75	1	I10	I^5	M10	M^5	AX10	AX^5
76	1	I12	I^6	M12	M^6	AX12	AX^6
77	1	I14	I^7	M14	M^7	AX14	AX^7
78	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
79	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
80	1	J0	J^0	N0	N^0	BX0	BX^0
81	1	J2	J^1	N2	N^1	BX2	BX^1
82	1	J4	J^2	N4	N^2	BX4	BX^2
83	1	J6	J^3	N6	N^3	BX6	BX^3
84	1	J8	J^4	N8	N^4	BX8	BX^4
85	1	J10	J^5	N10	N^5	BX10	BX^5
86	1	J12	J^6	N12	N^6	BX12	BX^6
87	1	J14	J^7	N14	N^7	BX14	BX^7
88	-	VCC	-	VCC	-	VCC	-
89	-	NC	-	NC	-	NC	-
90	-	GND	-	GND	-	GND	-
91	-	TMS	-	TMS	-	TMS	-
92	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
93	1	K14	K^7	O14	O^7	CX14	CX^7
94	1	K12	K^6	O12	O^6	CX12	CX^6
95	1	K10	K^5	O10	O^5	CX10	CX^5
96	1	K8	K^4	O8	O^4	CX8	CX^4
97	1	K6	K^3	O6	O^3	CX6	CX^3
98	1	K4	K^2	O4	O^2	CX4	CX^2
99	1	K2	K^1	O2	O^1	CX2	CX^1
100	1	K0	K^0	O0	O^0	CX0	CX^0

**ispMACH 4256V/B/C, 4384V/B/C, 4512V/B/C Logic Signal Connections:  
256-Ball ftBGA/fpBGA**

Ball Number	I/O Bank	ispMACH 4256V/B/C 128-I/O		ispMACH 4256V/B/C 160-I/O		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
-	-	-	-	-	-	VCC	-	VCC	-
-	-	GND	-	GND	-	GND	-	GND	-
C3	-	TDI	-	TDI	-	TDI	-	TDI	-
-	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
B1	0	C14	C^7	C14	C^9	C14	C^7	C14	C^7
F5	0	C12	C^6	C12	C^8	C12	C^6	C12	C^6
D3	0	C10	C^5	C10	C^7	C10	C^5	C10	C^5
C1	0	C8	C^4	C9	C^6	C8	C^4	C8	C^4
C2	0	C6	C^3	C8	C^5	C6	C^3	C6	C^3
E3	0	C4	C^2	C6	C^4	C4	C^2	C4	C^2
D2	0	C2	C^1	C4	C^3	C2	C^1	C2	C^1
F6	0	C0	C^0	C2	C^2	C0	C^0	C0	C^0
D1	0	NC	-	C1	C^1	F6	F^3	H0	H^0
E2	0	NC	-	C0	C^0	F4	F^2	H4	H^1
E4	0	NC	-	NC	-	D6	D^3	F4	F^2
G5	0	NC	-	NC	-	D4	D^2	F6	F^3
E1	0	NC	-	NC	-	NC	-	F8	F^4
-	0	-	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
-	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
F2	0	NC	-	NC	-	NC	-	F10	F^5
F1	0	NC	-	NC	-	D2	D^1	F12	F^6
G1	0	NC	-	NC	-	D0	D^0	F14	F^7
G6	0	NC	-	D14	D^9	F2	F^1	H8	H^2
G4	0	NC	-	D12	D^8	F0	F^0	H12	H^3
H6	0	D14	D^7	D10	D^7	E14	E^7	G14	G^7
G3	0	D12	D^6	D9	D^6	E12	E^6	G12	G^6
H5	0	D10	D^5	D8	D^5	E10	E^5	G10	G^5
G2	0	D8	D^4	D6	D^4	E8	E^4	G8	G^4
H1	0	D6	D^3	D4	D^3	E6	E^3	G6	G^3
H2	0	D4	D^2	D2	D^2	E4	E^2	G4	G^2
H3	0	D2	D^1	D1	D^1	E2	E^1	G2	G^1
H4	0	D0	D^0	D0	D^0	E0	E^0	G0	G^0
-	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
-	0	-	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
J4	0	E0	E^0	E0	E^0	H0	H^0	J0	J^0
J3	0	E2	E^1	E1	E^1	H2	H^1	J2	J^1
J2	0	E4	E^2	E2	E^2	H4	H^2	J4	J^2
J1	0	E6	E^3	E4	E^3	H6	H^3	J6	J^3
K1	0	E8	E^4	E6	E^4	H8	H^4	J8	J^4
J5	0	E10	E^5	E8	E^5	H10	H^5	J10	J^5
K2	0	E12	E^6	E9	E^6	H12	H^6	J12	J^6











## ispMACH 4000C (1.8V) Lead-Free Industrial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4256C	LC4256C-5FTN256AI	256	1.8	5	Lead-free ftBGA	256	128	I
	LC4256C-75FTN256AI	256	1.8	7.5	Lead-free ftBGA	256	128	I
	LC4256C-10FTN256AI	256	1.8	10	Lead-free ftBGA	256	128	I
	LC4256C-5FTN256BI	256	1.8	5	Lead-free ftBGA	256	160	I
	LC4256C-75FTN256BI	256	1.8	7.5	Lead-free ftBGA	256	160	I
	LC4256C-10FTN256BI	256	1.8	10	Lead-free ftBGA	256	160	I
	LC4256C-5FN256AI <sup>1</sup>	256	1.8	5	Lead-free fpBGA	256	128	I
	LC4256C-75FN256AI <sup>1</sup>	256	1.8	7.5	Lead-free fpBGA	256	128	I
	LC4256C-10FN256AI <sup>1</sup>	256	1.8	10	Lead-free fpBGA	256	128	I
	LC4256C-5FN256BI <sup>1</sup>	256	1.8	5	Lead-free fpBGA	256	160	I
	LC4256C-75FN256BI <sup>1</sup>	256	1.8	7.5	Lead-free fpBGA	256	160	I
	LC4256C-10FN256BI <sup>1</sup>	256	1.8	10	Lead-free fpBGA	256	160	I
	LC4256C-5TN176I	256	1.8	5	Lead-free TQFP	176	128	I
	LC4256C-75TN176I	256	1.8	7.5	Lead-free TQFP	176	128	I
	LC4256C-10TN176I	256	1.8	10	Lead-free TQFP	176	128	I
LC4384C	LC4384C-5FTN256I	384	1.8	5	Lead-free ftBGA	256	192	I
	LC4384C-75FTN256I	384	1.8	7.5	Lead-free ftBGA	256	192	I
	LC4384C-10FTN256I	384	1.8	10	Lead-free ftBGA	256	192	I
	LC4384C-5FN256I <sup>1</sup>	384	1.8	5	Lead-free fpBGA	256	192	I
	LC4384C-75FN256I <sup>1</sup>	384	1.8	7.5	Lead-free fpBGA	256	192	I
	LC4384C-10FN256I <sup>1</sup>	384	1.8	10	Lead-free fpBGA	256	192	I
	LC4384C-5TN176I	384	1.8	5	Lead-free TQFP	176	128	I
	LC4384C-75TN176I	384	1.8	7.5	Lead-free TQFP	176	128	I
LC4512C	LC4512C-5FTN256I	512	1.8	5	Lead-free ftBGA	256	208	I
	LC4512C-75FTN256I	512	1.8	7.5	Lead-free ftBGA	256	208	I
	LC4512C-10FTN256I	512	1.8	10	Lead-free ftBGA	256	208	I
	LC4512C-5FN256I <sup>1</sup>	512	1.8	5	Lead-free fpBGA	256	208	I
	LC4512C-75FN256I <sup>1</sup>	512	1.8	7.5	Lead-free fpBGA	256	208	I
	LC4512C-10FN256I <sup>1</sup>	512	1.8	10	Lead-free fpBGA	256	208	I
	LC4512C-5TN176I	512	1.8	5	Lead-free TQFP	176	128	I
	LC4512C-75TN176I	512	1.8	7.5	Lead-free TQFP	176	128	I
	LC4512C-10TN176I	512	1.8	10	Lead-free TQFP	176	128	I

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

## ispMACH 4000V (3.3V) Lead-Free Extended Temperature Devices

Device	Part Number	Macrocells	Voltage	$t_{PD}$	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-75TN48E	32	3.3	7.5	Lead-free TQFP	48	32	E
	LC4032V-75TN44E	32	3.3	7.5	Lead-free TQFP	44	30	E
LC4064V	LC4064V-75TN100E	64	3.3	7.5	Lead-free TQFP	100	64	E
	LC4064V-75TN48E	64	3.3	7.5	Lead-free TQFP	48	32	E
	LC4064V-75TN44E	64	3.3	7.5	Lead-free TQFP	44	30	E
LC4128V	LC4128V-75TN144E	128	3.3	7.5	Lead-free TQFP	144	96	E
	LC4128V-75TN128E	128	3.3	7.5	Lead-free TQFP	128	92	E
	LC4128V-75TN100E	128	3.3	7.5	Lead-free TQFP	100	64	E
LC4256V	LC4256V-75TN176E	256	3.3	7.5	Lead-free TQFP	176	128	E
	LC4256V-75TN144E	256	3.3	7.5	Lead-free TQFP	144	96	E
	LC4256V-75TN100E	256	3.3	7.5	Lead-free TQFP	100	64	E

**For Further Information**

In addition to this data sheet, the following technical notes may be helpful when designing with the ispMACH 4000V/B/C/Z family:

- TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#)
- TN1005, [Power Estimation in ispMACH 4000V/B/C/Z Devices](#)

**Revision History**

Date	Version	Change Summary
—	—	Previous Lattice releases.
July 2003	17z	Changed device status for LC4064ZC and LC4128ZC to production release and updated/added AC and DC parameters as well as ordering part numbers for LC4064ZC and LC4128ZC devices.
		Improved leakage current specifications for ispMACH 4000Z. For ispMACH 4000V/B/C IIL, IIH condition now includes 0V and 3.6V end points ( $0 \leq V_{IN} \leq 3.6V$ ).
		Added 132-ball chip scale BGA power supply and NC connections.
		Added 132-ball chip scale BGA logic signal connections for LC4064ZC, LC4128ZC and LC4256ZC devices.
		Added lead-free package designators.
October 2003	18z	Hot socketing characteristics footnote 1. has been enhanced; Insensitive to sequence of VCC or VCCO. However, assumes monotonic rise/fall rates for Vcc and Vcco, provided $(V_{IN} - VCCO) \leq 3.6V$ .
		Improved LC4064ZC $t_S$ to 2.5ns, $t_{ST}$ to 2.7ns and $f_{MAX}$ (Ext.) to 175MHz, LC4128ZC $t_{CO}$ to 3.5ns and $f_{MAX}$ (Ext.) to 161MHz (version v.2.1).
		Improved associated internal timing numbers and timing adders (version v.2.1).
		Added ispMACH 4000V/B/C/Z ORP Reference Tables.
		Enhanced ORP information in device pinout tables consistent with the ORP Combinations for I/O Blocks tables (table 6, 7, 8 and 9 in page 9-11).
		Corrected GLB/MC/Pad information in the 256-fpBGA pinouts for the LC4256V/B/C 160-I/O version.
		Added the ispMACH 4000 Family Speed Grade Offering table.
		Added the ispMACH 4128ZC Industrial and Automotive Device OPNs
December 2003	19z	Added the ispMACH 4032ZC and 4064ZC Industrial and Automotive Device OPNs

## Revision History (Cont.)

Date	Version	Change Summary
January 2004	20z	ispMACH 4000Z data sheet status changed from preliminary to final. Documents production release of the ispMACH 4256Z device.
		Added new feature - ispMACH 4000Z supports operation down to 1.6V.
		Added lead-free packaging ordering part numbers for the ispMACH 4000Z/C/V devices.
April 2004	21z	Updated $I_{PU}$ (I/O Weak Pull-up Resistor Current) max. specification for the ispMACH 4000V/B/C; -150 $\mu$ A to -200 $\mu$ A.
November 2004	22z	Added User Electronic Signature section.
		Added ispMACH 4000B (2.5V) Lead-Free Ordering Part Numbers.
December 2004	22z.1	Updated Further Information section.
February 2006	22z.2	Clarification to ispMACH 4000Z Input Leakage ( $I_{IH}$ ) specification.
March 2007	22.3	Updated ispMACH 4000 Introduction section.
		Updated Signal Descriptions table.
June 2007	22.4	Updated Features bullets to include reference to "LA" automotive data sheet under the "Broad Device Offering" bullet.
		Added footnote 1 to Part Number Description to reference the "LA" automotive data sheet.
		Changed device temperature references from 'Automotive' to "Extended Temperature" for non-AEC-Q100 qualified devices.
November 2007	23.0	Added 256-ftBGA package Ordering Part Number information per PCN#14A-07.
May 2009	23.1	Correction to $t_{CW}$ , $t_{GW}$ , $t_{WIR}$ and $f_{MAX}$ parameters in ispMACH 4000Z External Switching Characteristics table.
		Correction to $t_{CW}$ , $t_{GW}$ , $t_{WIR}$ and $f_{MAX}$ parameters in ispMACH 4000V/B/C External Switching Characteristics table.